















- ► PTH/THT Lamp
- ▶ 5mm Round 8.7t
- ► Cool White (8200K)

NOW46L05Z (Bulk) NOW46L05ZT (Taping)





FEATURES:





- Package: PTH/THT LED Lamp 5mm Round 8.7t
- Forward Current: 20mA
- Forward Voltage (typ.): 3.2V
- Luminous Intensity (typ.): 20000mcd@20mA
- Colour: Cool White
- Colour Temperature: 8200K (X=0.2900; Y=0.3100)
- Viewing angle: 20°
- Electrostatics Discharge (ESD): 2000V
- **Materials:**
 - Die: InGaN
 - Resin: Epoxy (Water Clear)
- Operating Temperature: -40~+85°C
- Storage Temperature: -40~+100°C
- **Grouping parameters:**
 - Forward voltage
 - Luminous intensity
 - **CIE Chromaticity**
- Soldering methods: Hand; Soldering Heat (DIP)
- MSL Level: acc. to JEDEC Level 3
- Packing: 500pcs/bulk; 2000pcs/tape (ammo pack)

APPLICATIONS:

- Indicator
- Switch
- Signal Light



CHARACTERISTICS:

Absolute Maximum Characteristics (Ta=25°C)

Parameter	Symbol	Ratings	Unit
Forward Current	IF	30	mA
Peak Forward Current Duty 1/10@1KHz	I _{FP}	100	mA
Reverse Current @5V	I _R	10	μΑ
Power Dissipation	P _D	85	mW
Electrostatics Discharge	ESD	2000	V
Operating Temperature	T _{OPR}	-40~+85	°C
Storage Temperature	T _{STG}	-40~+100	°C

Electrical & Optical Characteristics (Ta=25°C)

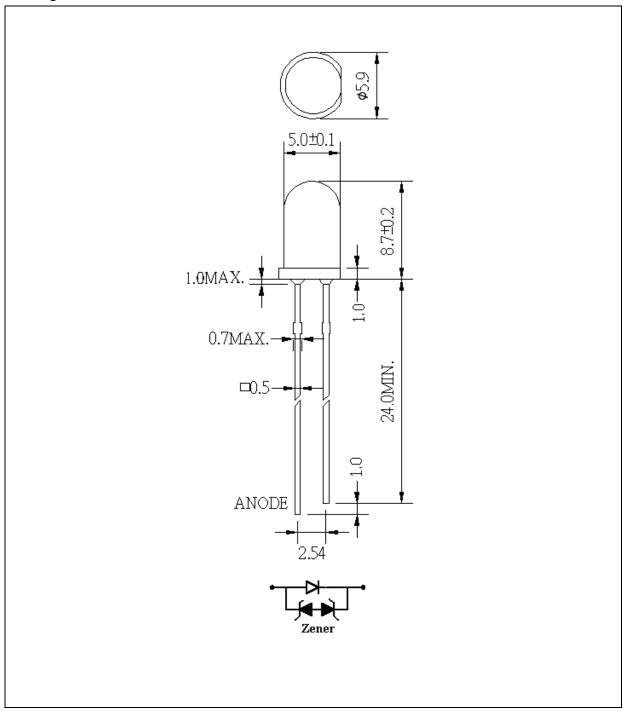
Parameter	Symbol	Values			Unit	Test	
Parameter	Зуппоп	Min.	Тур. Мах.		Offic	Condition	
Forward Voltage	V_{F}	2.8	3.2	3.5	V	I _F =20mA	
Luminous Intensity	lv	16500	20000	32000	mcd	I _F =20mA	
Chromaticity	Х		0.2900			I _F =20mA	
Coordinates	Υ		0.3100				
Colour Temperature	ССТ		8200		К	I _F =20mA	
Viewing Angle	2θ _{1/2}		20		deg	I _F =20mA	

^{1.} Luminous intensity (I_V) ±15%, Forward Voltage (V_F) ±0.1V



OUTLINE DIMENSION:

Package Dimension:



- 1. All dimensions are in millimetre (mm).
- 2. Tolerance ±0.25mm, unless otherwise noted.



BINNING GROUPS:

Forward Voltage Classifications (I_F = 20mA):

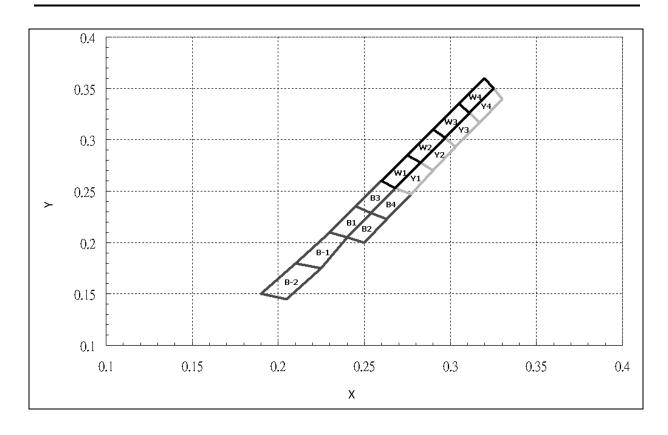
Code	Min.	Max.	Unit
J	2.8	3.0	
K	3.0	3.2	V
L	3.2	3.4	V
M	3.4	3.6	

Luminous Intensity Classifications (I_F = 20mA):

Code	Min.	Max.	Unit	
23	16500	25000		
24	25000	32000	mcd	



CIE CHROMATICITY DIAGRAM:

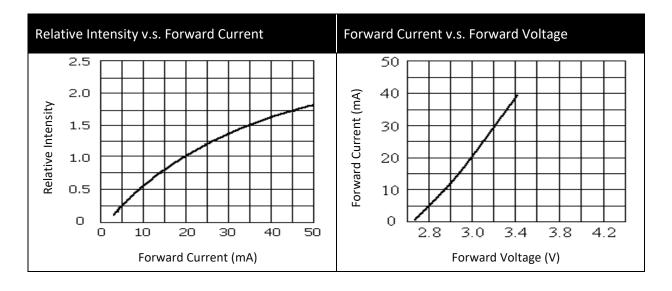


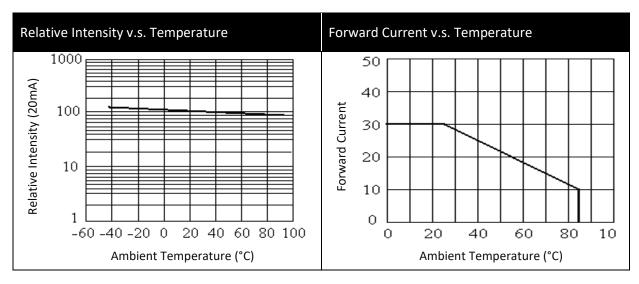
Chromaticity Coordinates Classifications (I_F = 20mA):

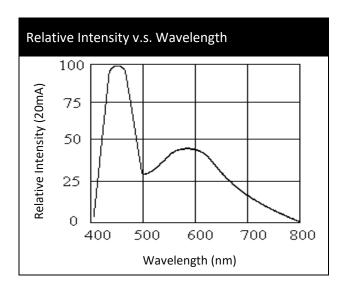
	1	l	2		3		4	
	Х	Υ	Х	Υ	Х	Υ	Х	Υ
W1	0.2600	0.2600	0.2750	0.2850	0.2830	0.2780	0.2680	0.2530
W2	0.2750	0.2850	0.2900	0.3100	0.2970	0.3020	0.2830	0.2780
W3	0.2900	0.3100	0.3050	0.3350	0.3110	0.3260	0.2970	0.3020
W4	0.3050	0.3350	0.3200	0.3600	0.3250	0.3500	0.3110	0.3260



ELECTRO-OPTICAL CHARACTERISTICS:







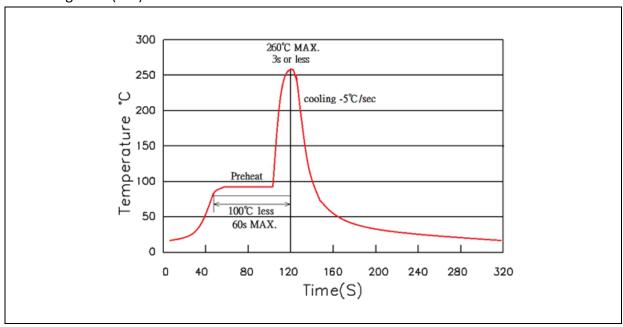


RECOMMENDED SOLDERING PROFILE:

Hand Solder (Solder Iron):

- Temperature at tip of iron: 350°C Max.
- Soldering Time: 3 seconds ± 1 sec.

Soldering Heat (DIP):

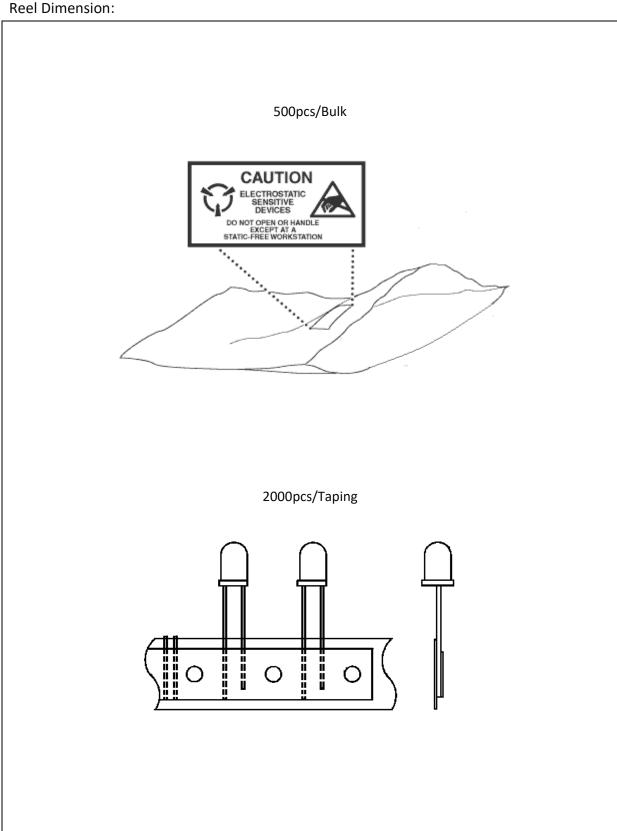


Note:

- 1. Maximum reflow soldering: 1 time.
- 2. Before, during, and after soldering, should not apply stress on the components and PCB board.



PACKING SPECIFICATION:





PRECAUTIONS OF USE:

Storage:

It is recommended to store the products in the following conditions:

- Humidity: 60% R.H. Max.
- Temperature: 5°C~30°C (41°F ~86°F).

Shelf life in sealed bag: 12 months at 5°C~30°C and <60% R.H.

Once the package is opened, the products should be used within a week. Otherwise, they should be kept in a damp-proof box with descanting agent <10% R.H. and apply baking before use.

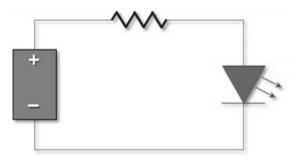
Baking:

It is recommended to bake the LED before soldering if the pack has been unsealed for longer than 24hrs. The suggested baking conditions are as followings:

• 60±5°C x 24hrs and <5%RH, taped / reel package.

It's normal to see slight color fading of carrier (light yellow) after baking in process.

Testing Circuit:



Must apply resistor(s) for protection (over current proof).

Cleaning:

Use alcohol-based cleaning solvents such as isopropyl alcohol to clean the LED carrier / package. Avoid putting any stress force directly on to the LED lens.

ESD (Electrostatic Discharge):

Static Electricity or power surge will damage the LED. Use of a conductive wrist band or anti-electrosatic glove is recommended when handing the LED all time. All devices, equipment, machinery, work tables, and storage racks must be properly grounded.

In the events of manual working in process, make sure the devices are well protected from ESD at any time.



REVISION RECORD:

Version	Date	Summary of Revision
A1.0	20/03/2023	Datasheet set-up.